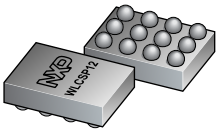

SOT1390-12

WLCSP12, wafer level chip-size package, 12 terminals, 0.4 mm pitch, 1.62 mm x 1.19 mm x 0.56 mm body

14 October 2022 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP12
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	S (silicon)
Mounting method type	S (surface mount)
Issue date	04-07-2022
Manufacturer package code	98ASA01954D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.59	1.62	1.65	
package width	1.16	1.19	1.22	
seated height	-	0.56	0.6	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	12	-	

WLCSP12, wafer level chip-size package, 12 terminals, 0.4 mm pitch, 1.62 mm x 1.19 mm x 0.56 mm body

2 Package outline

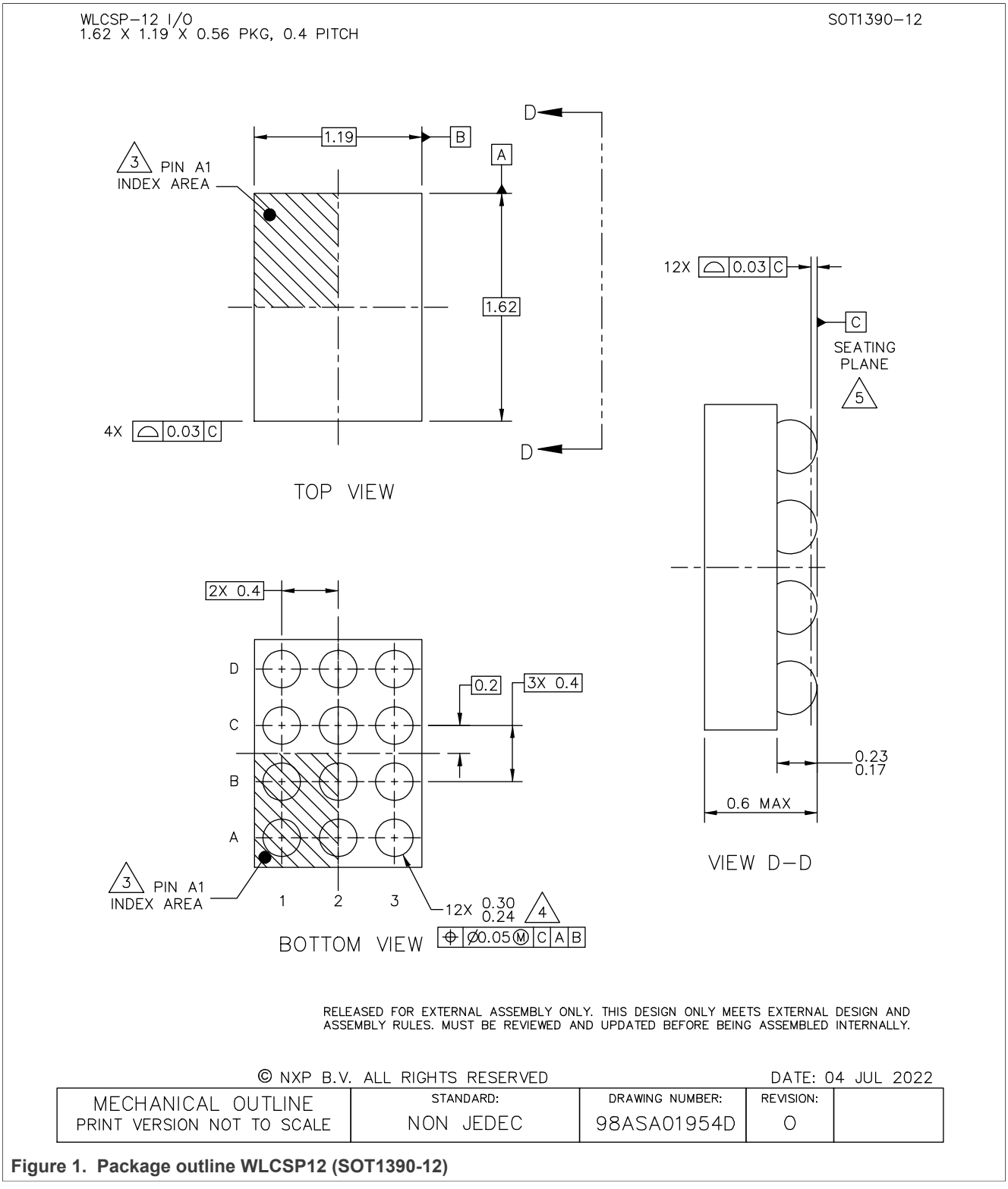

Figure 1. Package outline WLCSP12 (SOT1390-12)

3 Soldering

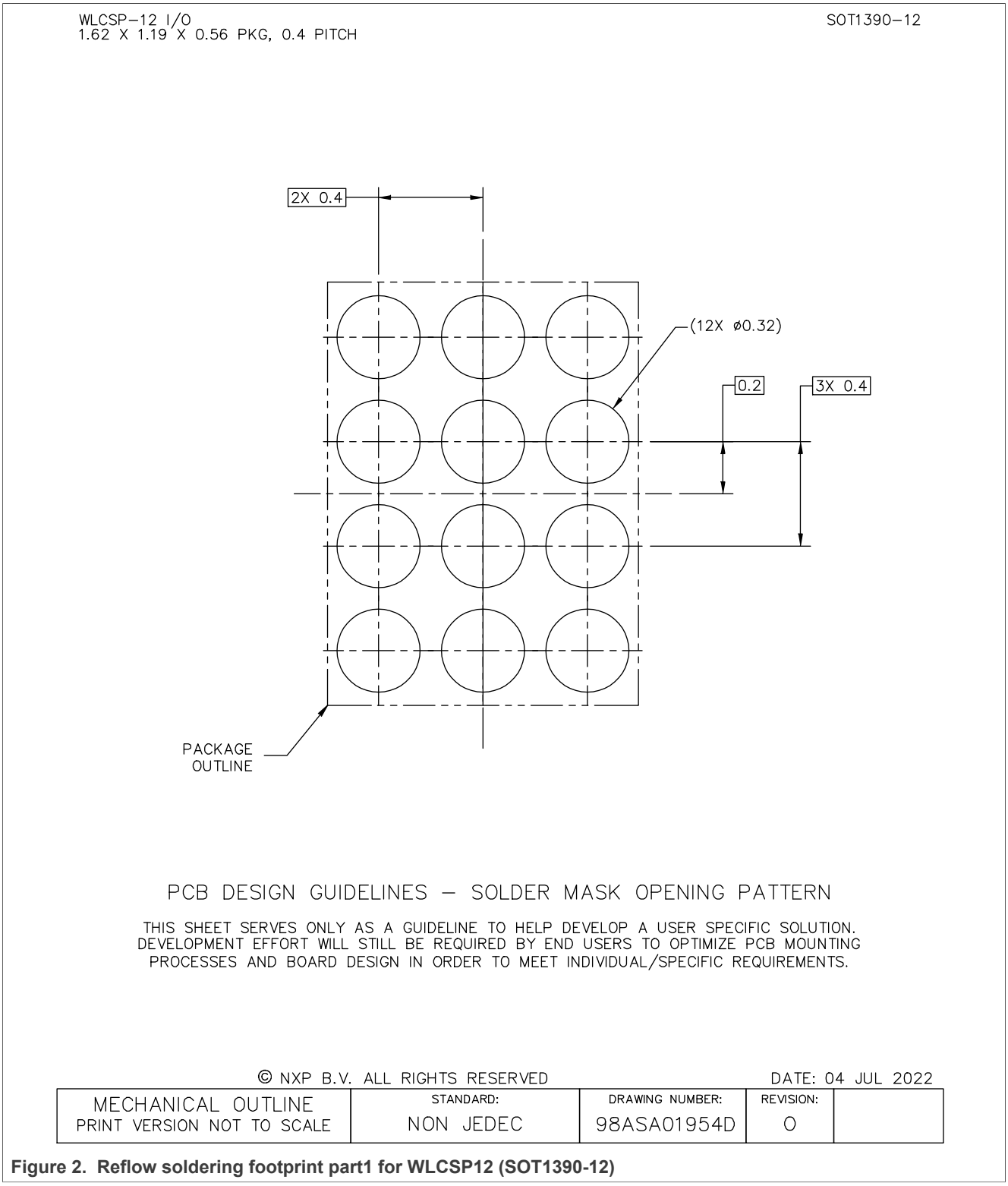

Figure 2. Reflow soldering footprint part1 for WLCSP12 (SOT1390-12)

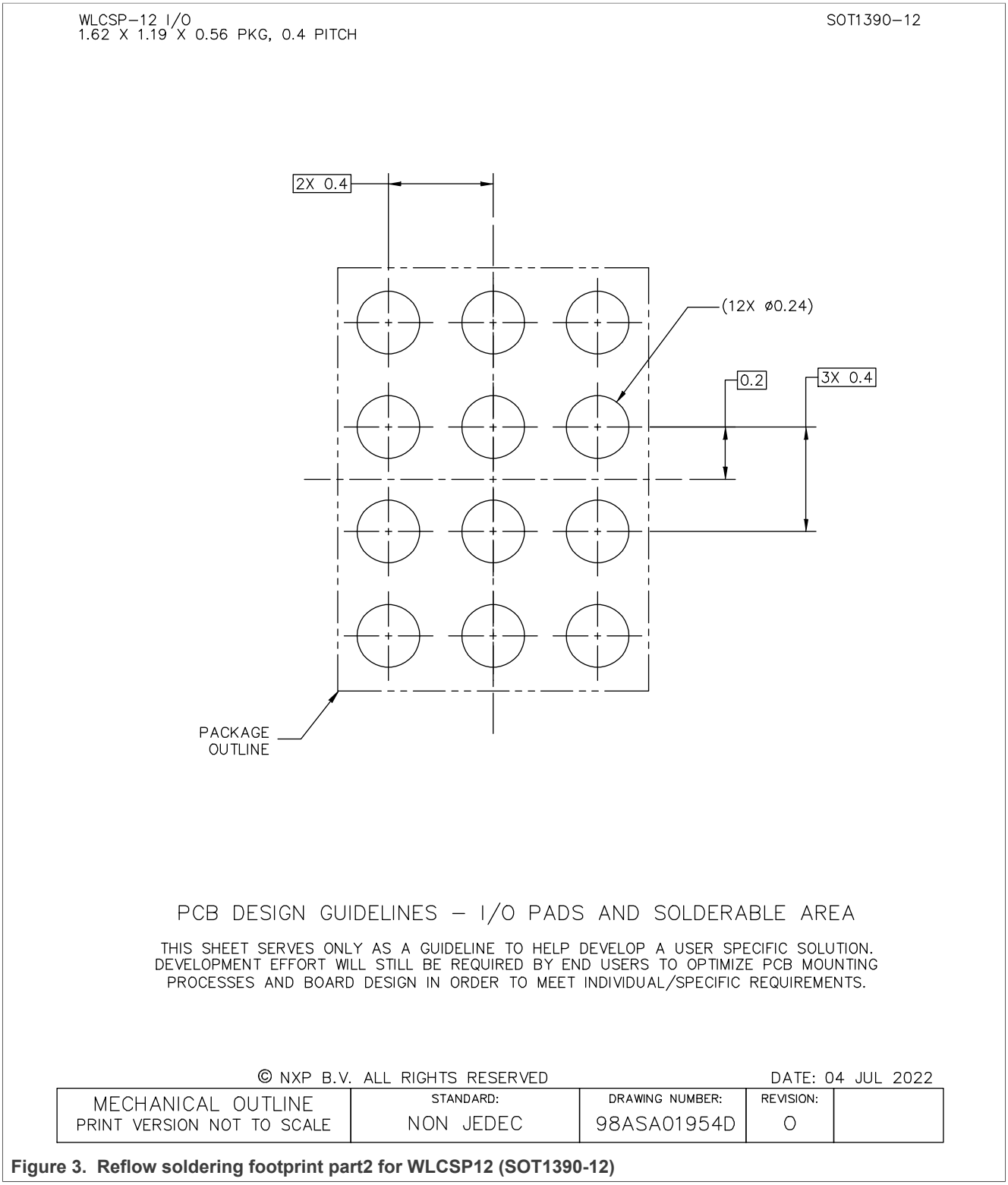

Figure 3. Reflow soldering footprint part2 for WLCSP12 (SOT1390-12)

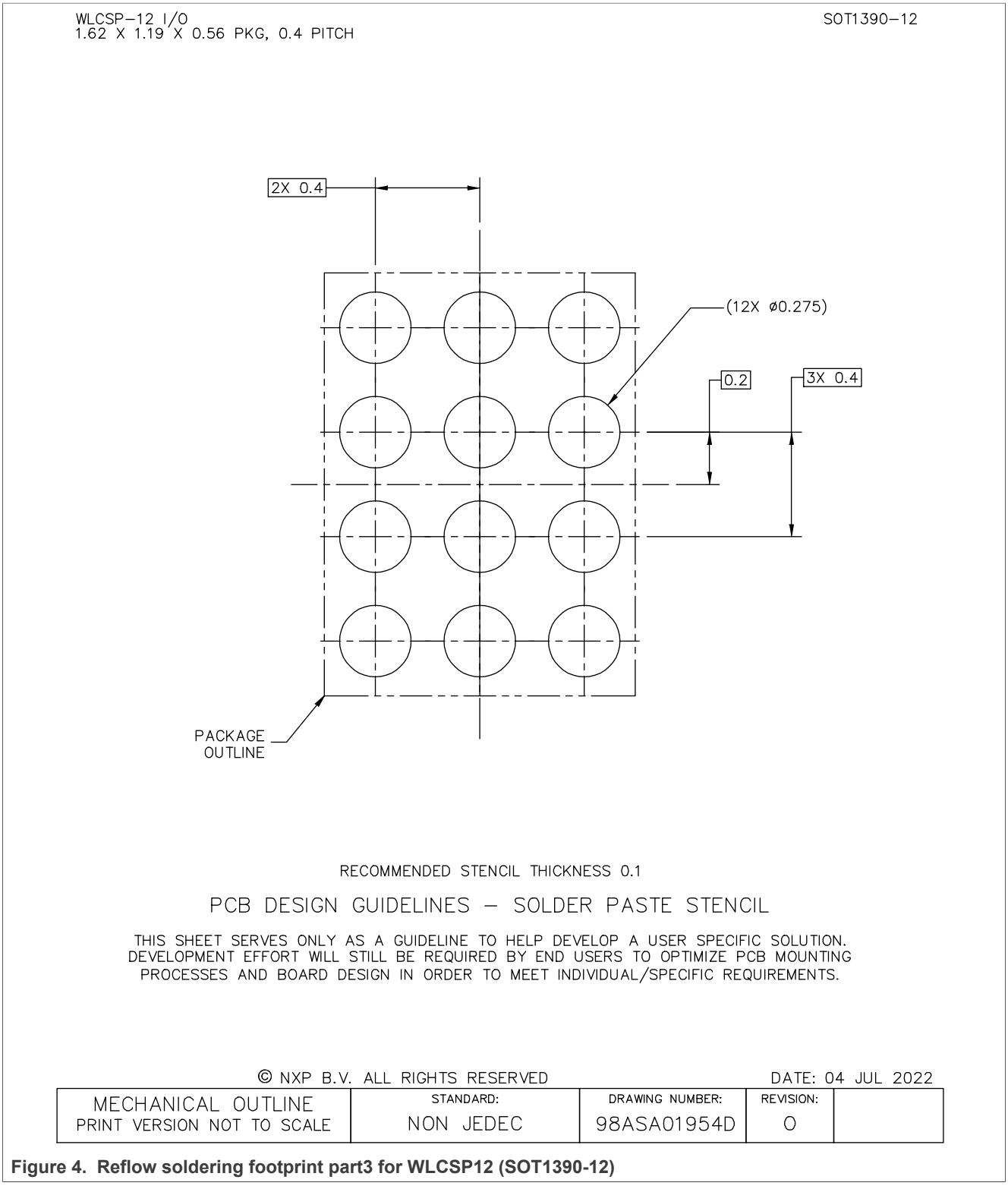

Figure 4. Reflow soldering footprint part3 for WLCSP12 (SOT1390-12)

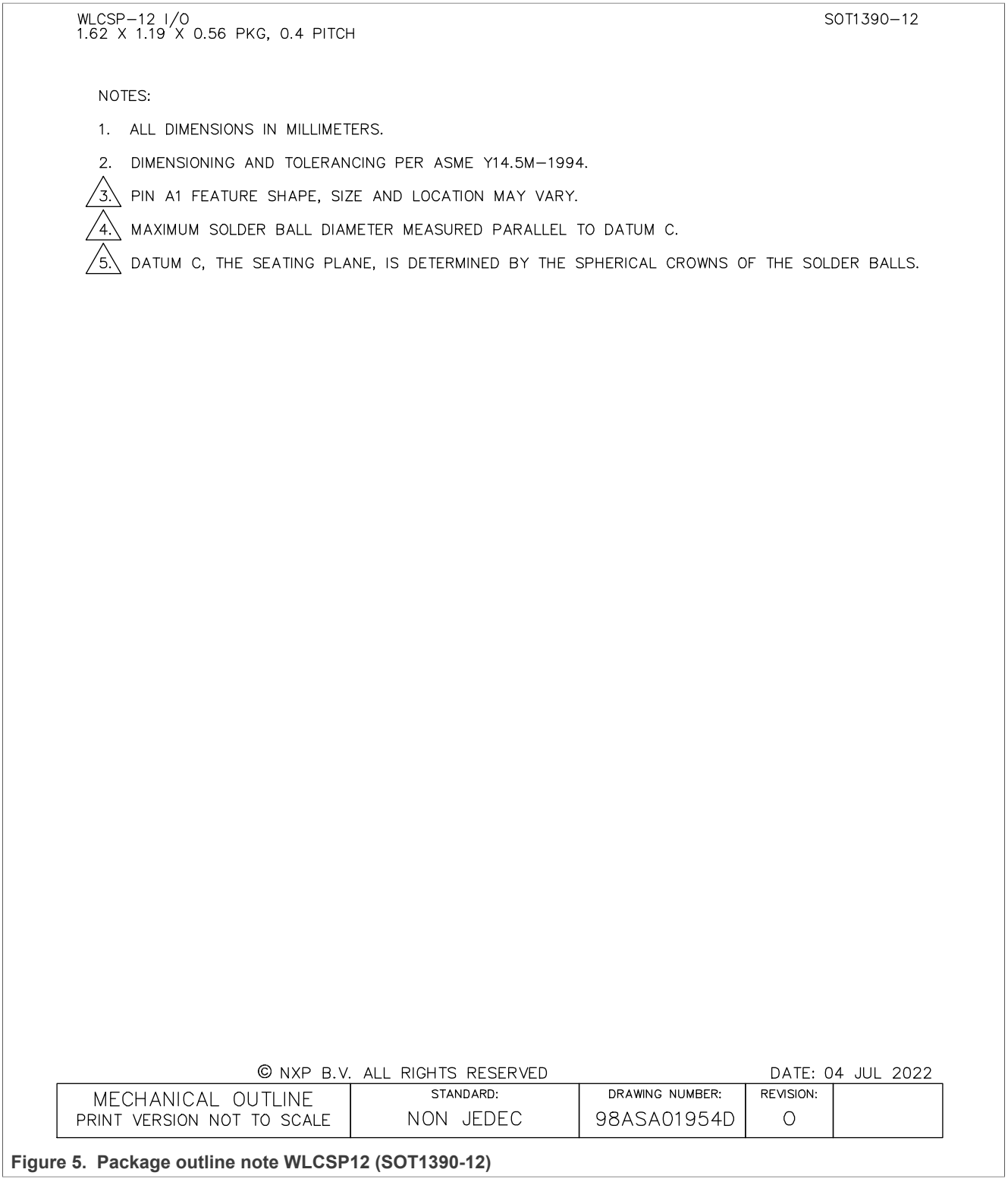

Figure 5. Package outline note WLCSP12 (SOT1390-12)

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SOT1390-12

WLCSP12, wafer level chip-size package, 12 terminals, 0.4 mm pitch, 1.62 mm x 1.19 mm x 0.56 mm body

Contents

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Date of release: 14 October 2022